

STANDALONE WAFER PREALIGNER

LPA312-3

Innovative, high-performance, all-in-one design eliminates external controller and interconnecting cables while maintaining drop-in compatibility

Driven by ultra low inertia brushless motors for **smooth, instant response**

Advanced scanning electronics capable of detecting **transparent, semi-transparent and opaque objects** without mechanical repositioning between different wafer sizes

Motion control software featuring a comprehensive set of commonly used commands enabling **compatibility and interface with a variety of semiconductor platforms**

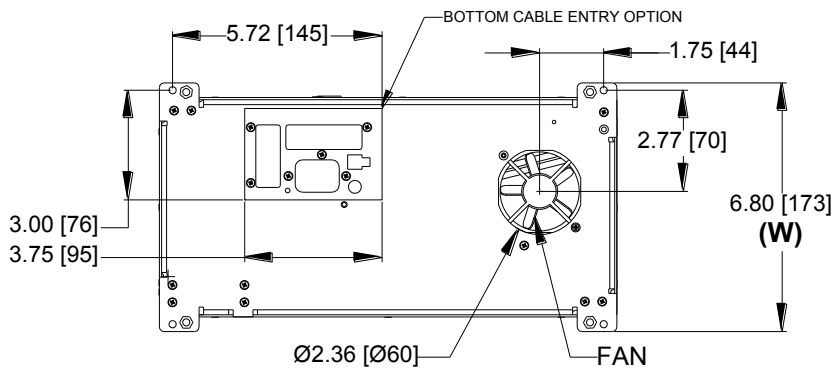
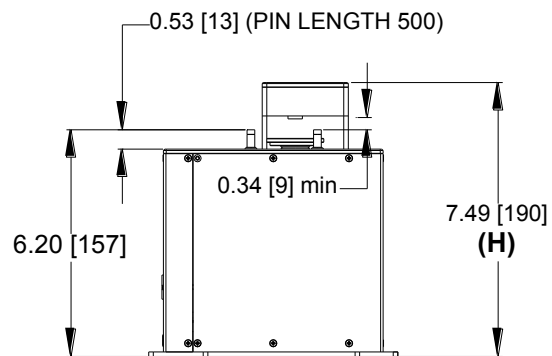
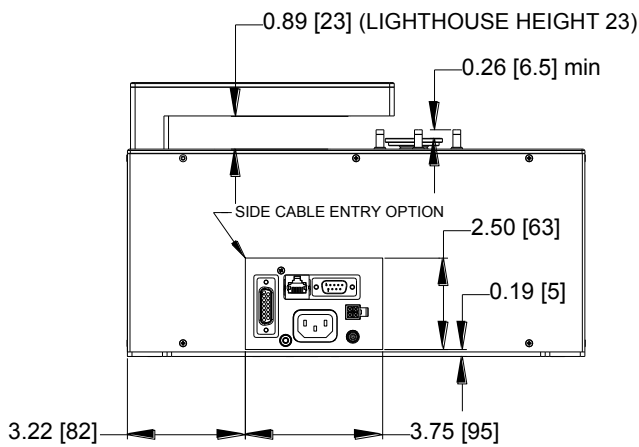
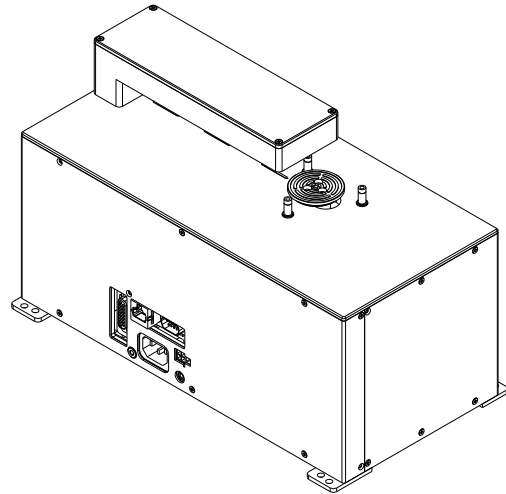
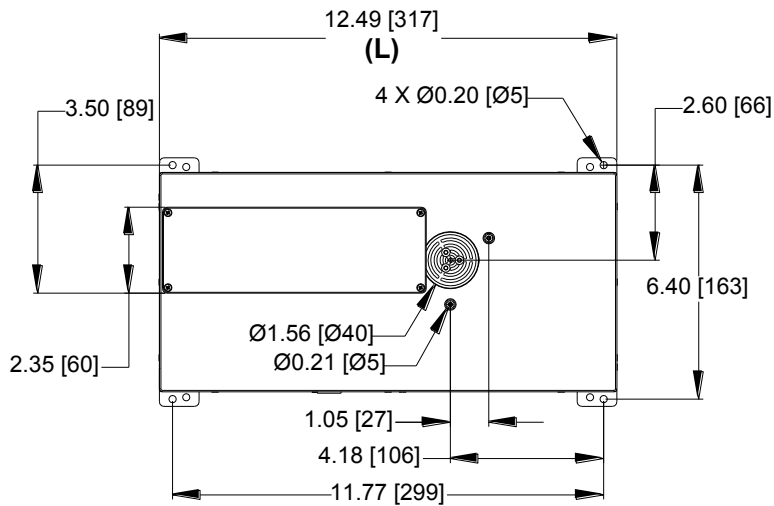
Typical alignment cycle time of less than four seconds facilitates the achievement of **maximum system throughput**



LPA312-3 SPECIFICATIONS

| | | |
|------------------------------------|--------------------------|---|
| Wafer Diameter | | 3", 100mm, 125mm, 150mm, 200mm, 300mm |
| Wafer Opacity | | Transparent, Semi-Transparent, Opaque |
| Square Substrates | | Applicable |
| Wafer Handling | | Vacuum Chuck and Pins |
| Centering Accuracy | | ±25um on the Prealigner Chuck |
| Angular Accuracy (3 Sigma) | 10000 CPR Encoder | ±0.04° on the Prealigner Chuck |
| | 24000 CPR Encoder | ±0.02° on the Prealigner Chuck |
| Servo Axes | | Three |
| Host Communication | | RS232, Ethernet |
| Max Initial Wafer Offset | | 12mm |
| Body Dimensions (W x L x H) | | 173mm x 317mm x 190mm |
| Footprint Compatibility | | LPA812-3, LPA1218-3 LPA8ET-3, LPA12ET-3 |
| Weight | | 5.50kg |
| Facilities Required | | 100-240VAC, 50/60Hz, 48VA, or 24VDC/2A Vacuum 12" Hg |
| Flat/Notch Compatibility | | SEMI Standards Compliant |
| Cleanliness | | Class 1 |
| MTBF | | More than 70000 hours |

LPA312-3 GENERAL DIMENSIONS



NOTE: All Dimensions — inch [mm]

For model numbers and options download: [LPA Series Prealigners Ordering Guide.pdf](#)